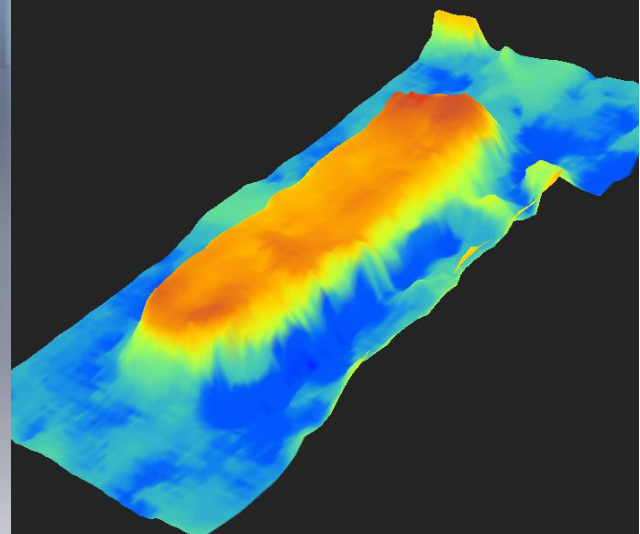# VISCOM
vision technology

Solder Paste Inspection System (SPI) for In-Line Manufacturing

VISCOM

iS6052

vAI
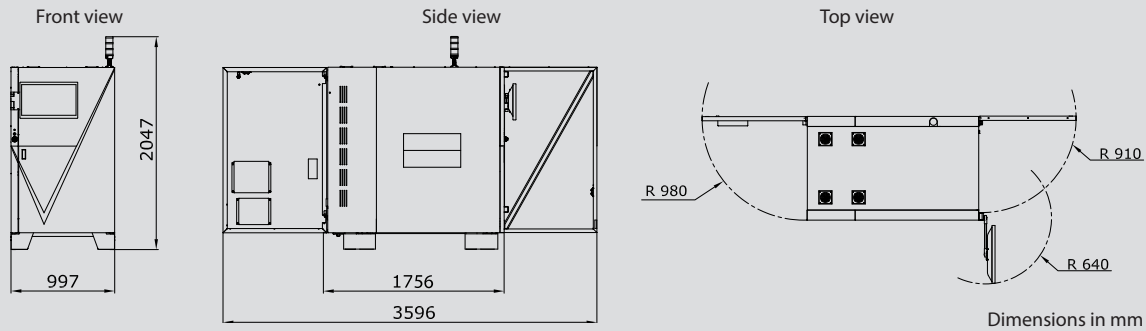
iS6052 SPI

Economical technology for reliable solder and sinter paste inspection

3D SPI

VISCOM
vision technology

Technical Specifications
iS6052 SPI

Front view	Side view	Top view
2047 / 997	1756 / 3596	R 980 / R 910 / R 640

Dimensions in mm

	iS6052 SPI	
Inspection Scope		Solder paste deposits (stencil printing or dispensing technology, up to pad sizes for 01005 components); sinter paste, adhesives, surface, height, print displacement, smearing, shape, coplanarity, open area analysis, OCR, DMCw
Camera technology		XM SPI
	3D Sensor Technology	
	Z-resolution	0,1 μm
	Z-range	Up to 5mm
	Angled view cameras	
	Number of megapixel cameras	4
	Orthogonal camera	
	Resolution	12 μm
	Field of view	58 mm x 58 mm (2.2" x 2.2")
Inspection Speed		Up to 80 cm²/s
Software	User interface	Viscom vVision
	Statistical process control	Viscom vSPC/SPC, open interface (optional)
	Verification station	Viscom vVerify
	Remote diagnosis	Viscom SRC (optional)
	Programming station	Viscom PST34 (optional)
System computer	Operating system	Windows®
	Processor	Intel®Core™i7
PCB handling	PCB dimensions	508 mm x 508 mm (20" x 20")
	PCB support	Optional
	Transport height	900 - 950 mm ± 20 mm (35.4" - 37.4" ± 0.8")
	Width adjustment	Automatic
	Transport concept	Single-track transport system, dual-lane option available
	PCB clamping	Pneumatic
	Upper transport clearance	50 mm (2")
	Lower transport clearance	50 mm (2"); 40 mm (1.6") with PCB support
Other system data	Positioning unit	Synchronous linear motor
	Interfaces	SMEMA, Hermes
	Power requirements	230/400 V, 50 Hz, 3P/N/PE +/- 10%; 4 - 6 bar working pressure
	System dimensions	997 mm x 1756 mm x 1753 mm (39.3" x 69.1" x 69") (W x D x H)
	Weight	Approx. 1060 kg (2337 lbs)

www.viscom.com